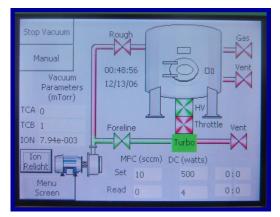


Hummer[®] BC-20 Series

ONE SYSTEM IN A FAMILY OF PLANAR MAGNETRON SPUTTERING SYSTEMS

THIN FILM DEPOSITION OF METALS AND INSULATORS





TOUCH-PANEL SYSTEM CONTROL

Vacuum and Process Control all in one. Functions are clearly displayed

QUARTZING CV DOT MATRIX FAILURE ANALYSIS MATERIALS RESEARCH MICROELECTRONICS RE-

BC Systems are available in sizes; 16", 20", 24" and 30" D-style chambers

The **HUMMER BC-20** sputter coater combines a high degree of process control and flexibility with ease of operation.

THIN FILM RESEARCH - FAILURE ANALYSIS - PILOT PRODUCTION

PLANAR MAGNETRON SOURCE

TARGET DIAMETER -

3" Standard, Optional - 2" & 4" diameter sources and Multiple sources **TARGET THICKNESS** - 1/16 to 1/4" standard **TARGET MATERIALS** - Metals and / or insulators **SOURCE MOUNTING** - Quick coupling to chamber, shutters, shields between sources as necessary **POWER SUPPLY** - 300 watts, 13.56 MHz. Standard

Optional - 600, 1000 watts RF at 13.56 MHz. 1500 Watts Standard, Optional - 2500 Watts DC, or various combinations of supplies **COOLING WATER** - .2 to 10 GPM required. Optional - Recirculation sys-

tem **TARGET MOUNTING** - Mechanical clamp or magnetic keeper depending upon requirement

HUMMER[®] BC-20 OVERALL SYSTEM

CHAMBER - 304 Stainless steel, 20" ID nominal, aluminum door, 4" Door view port, roughing, High Vacuum pump and instrument ports

CONTROL - Siemens S7-200 Series PLC control for each vacuum function and sputtering source. Fully integrated with easy "Touch-Panel" control pad for diagnostic and setting system parameters

DESIGN - Floor mount cabinet on casters with leveling pads **SAFETY INTERLOCKS** - Water, door and vacuum interlocks.

ELECTRICAL REQUIREMENTS - 40-75 AMP, 208-240 Volt,

40-75 AMP, 208-240 Volt, 50/60 HZ

SPUTTERING - Standard top down sputtering. Optional - Sputter-up or horizontal sputter **AUTOMATIC SEQUENCING** -

IONIZATION SPECIES

GAS REQUIREMENTS - Argon

REACTIVE SPECIES - Optional

regulated from 5 to 20 PSI

OPERATING PRESSURE -

 2×10^{-3} to 5×10^{-2}

Standard

VACUUM SYSTEM

PUMPING - Roughing pump and Turbo molecular pump - Standard Optional - Cryo pump or Larger pumps

VACUUM GAUGING - Convectron gauges (2), Ion gauge (1). Atmosphere to 1 x 10⁻⁸ TORR VALVES - Electro-Pneumatic actuated High Vacuum/Throttle valve between pump and chamber. Fore-line and chamber roughing isolation valves. Pneumatic air or nitrogen (clean, dry) operating at 60-PSI. GAS CONTROL - Mass Flow Controller (1) 100 sccm. Optional - Gases (3) maximum, for mixing and reactive gas sputtering





STAGE FIXTURE

SIZE - 2", 3", 4", 6", 8", 12" or 16" MOTION -360° rotation standard. Optional - Variable angle of incidence to sputter source COOLING - Optional REVERSE SPUTTER/ETCH - Optional HEATED - Optional to 900° Celsius

SOURCE OPTIONS

Anatech USA offers alternatives for source configuration. Contact our sales staff.



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Anatech USA Web Site: www.anatechusa.com

E-Mail: info@anatechusa.com

HUMMER[®] BC-20

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BOX COATER MAGNETRON SPUTTER SOURCES

Source configuration is available in Round or Linear planar magnetron designs. Sources are "Flex-Mounted" for 0-30° angle of incidence adjustability. Source shutter options include: Manually operated shutter assembly or Pneumatically actuated.

Anatech USA Web Site: www.anatechusa.com

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